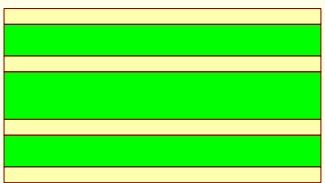


PCB Layer Stack-Up

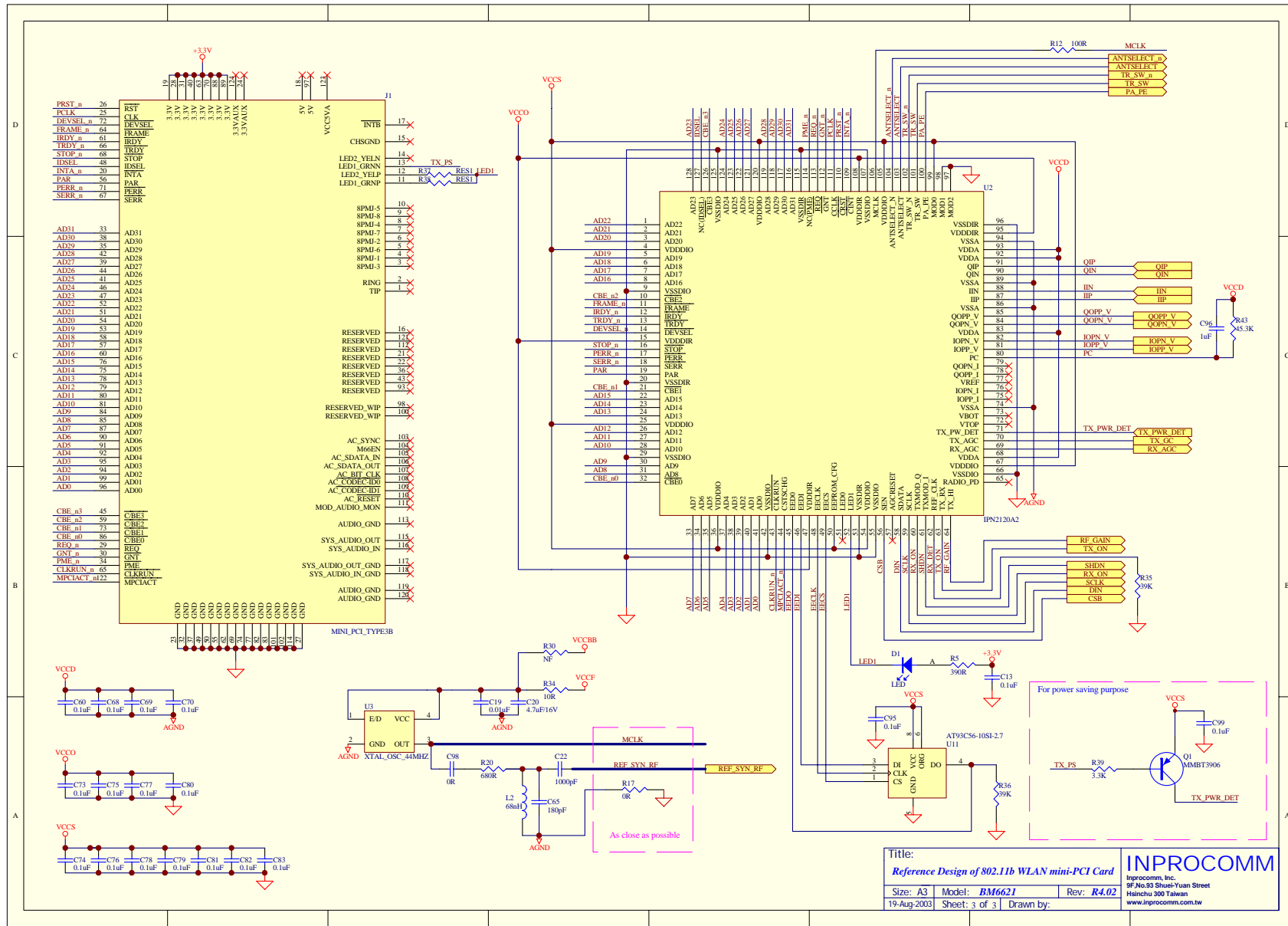
- Top Layer - Component Side; Signal Plane
- Mid Layer 1 - Non-Signal Ground Solid Plane
- Mid Layer 2 - Power/Ground Solid Plane
- Bottom Layer - Non-Component Side; Signal Solid Plane



Material	Thickness
0.5oz Cu+ Gold Plating	0.0007"
PrePreg FR4	0.006"
1.0oz Cu	0.0014"
Core FR4	0.0238" (Adjustable to finish the total thickness)
1.0oz Cu	0.0014"
PrePreg FR4	0.006"
0.5oz Cu+ Gold Plating	0.0007"

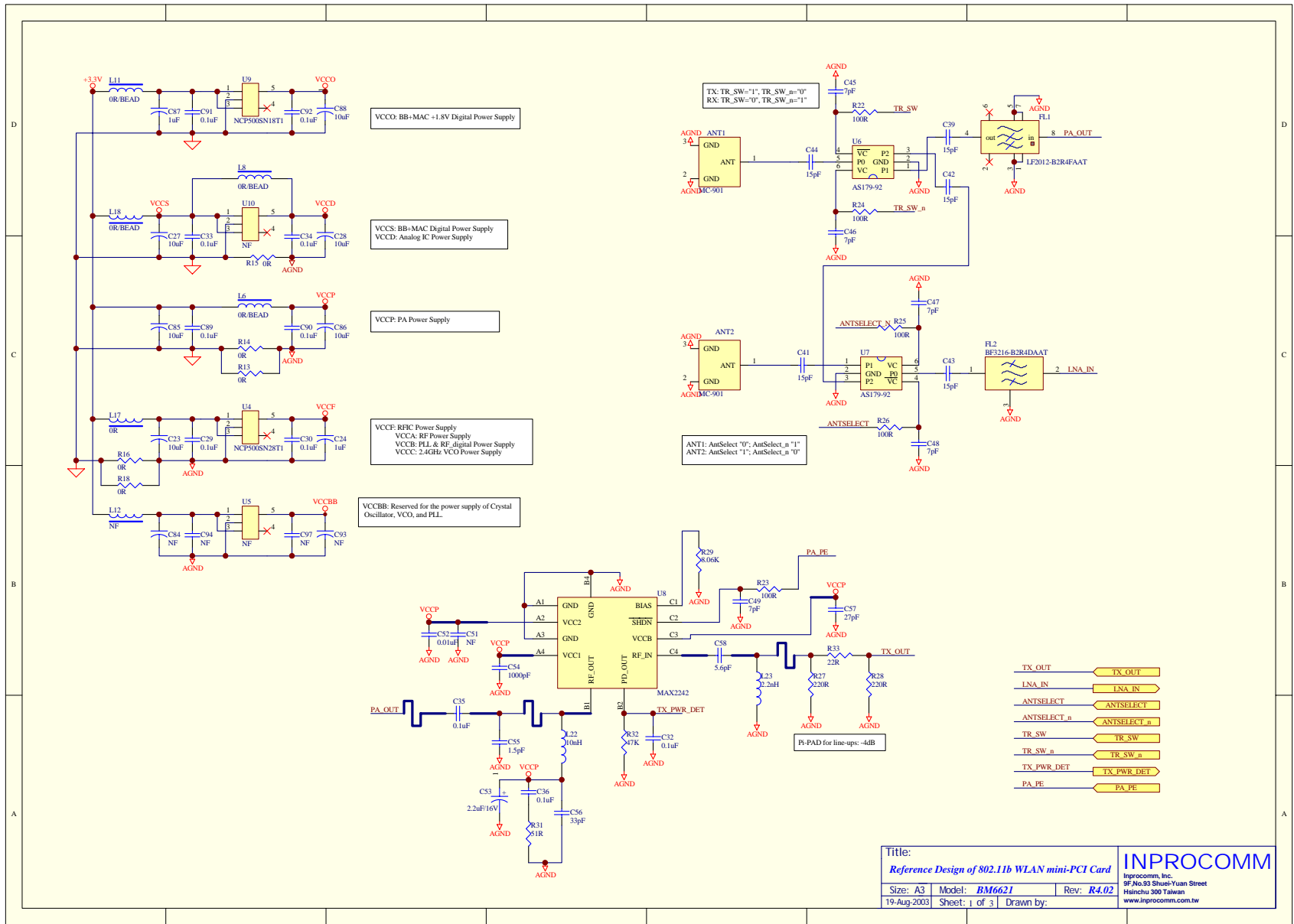
Finished Total Thickness: 40mil

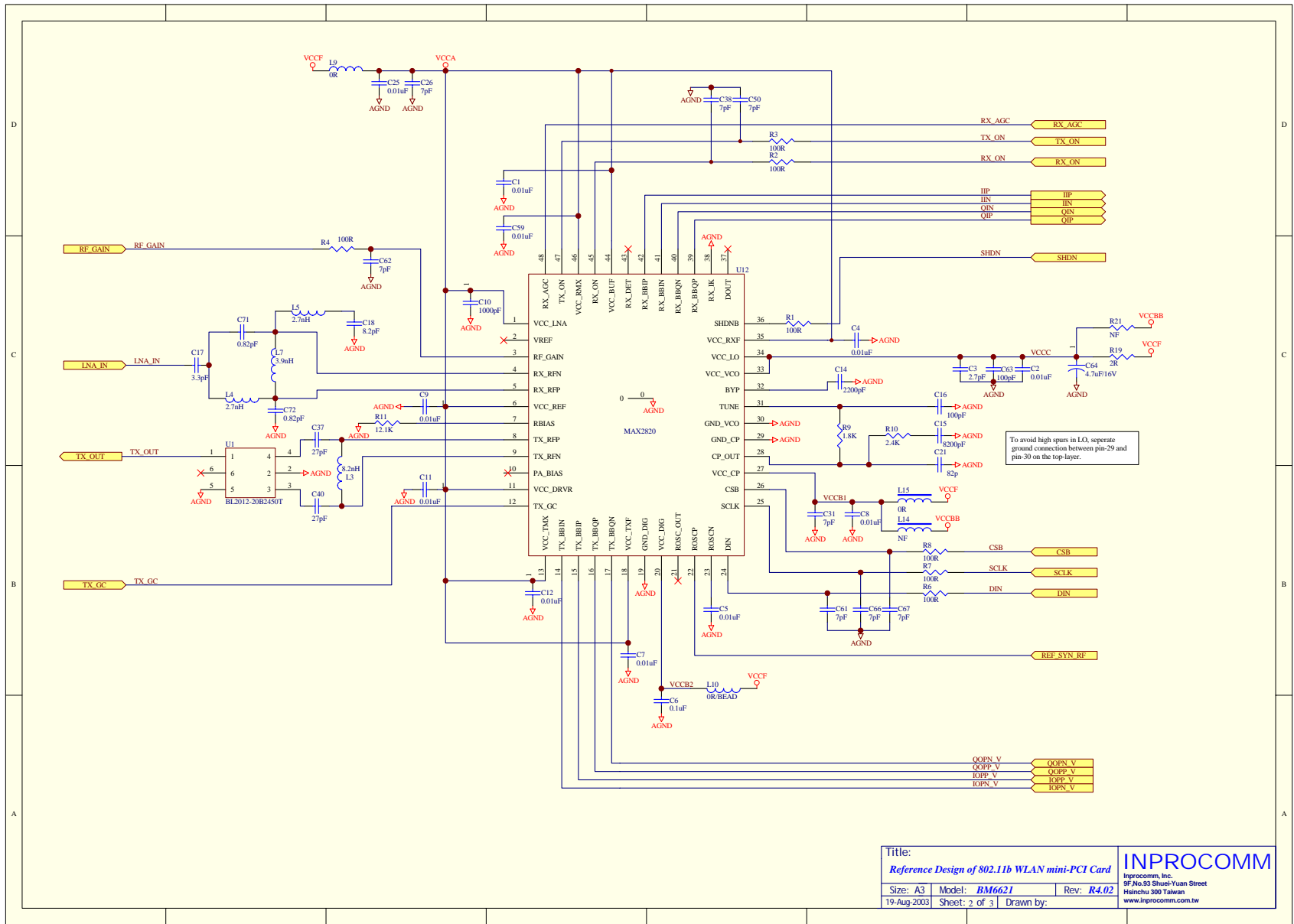
Dielectric Constant: 4.6
Fifty-Ohm Co-Planar Waveguide: 0.010" Line Width, 0.010" Gap Width



Title:
Reference Design of 802.11b WLAN mini-PCI Card
 Size: A3 Model: BM6621 Rev: R4.02
 19-Aug-2003 Sheet: 3 of 3 Drawn by:

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 Hsinchu 300 Taiwan
 www.inprocomm.com.tw





Title:
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 Size: A3 Model: BM6621 Rev: R4.02
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